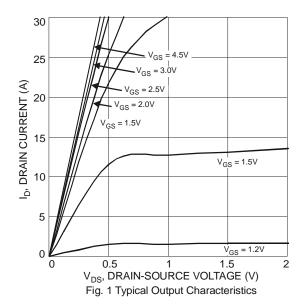


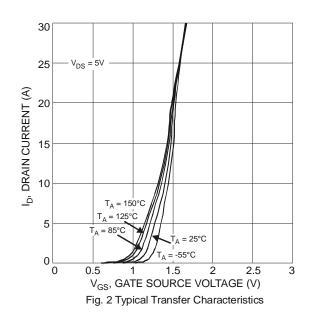
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 5)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	1	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = 25°C	I _{DSS}	-	-	1.0	μΑ	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±10	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	V _{GS(th)}	0.4	0.72	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance			11	14.5	mΩ	$V_{GS} = 4.5V, I_D = 9.4A$	
Static Drain-Source On-Nesistance	R _{DS (ON)}		13	16.5	111 2 2	$V_{GS} = 2.5V, I_D = 8.3A$	
Forward Transfer Admittance	Y _{fs}	-	19	-	S	$V_{DS} = 5V, I_{D} = 9.4A$	
Diode Forward Voltage	V_{SD}	-	0.65	1.2	V	$V_{GS} = 0V, I_{S} = 1.3A$	
DYNAMIC CHARACTERISTICS (Note 6)							
Input Capacitance	Ciss	-	1495	-	pF	$V_{DS} = 10V, V_{GS} = 0V,$ - f = 1.0MHz	
Output Capacitance	Coss	-	161	-	pF		
Reverse Transfer Capacitance	C_{rss}	-	152	-	pF		
Gate Resistance	R_g	-	1.42	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Q_{g}	-	16.5	·	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_{D} = 9.4A$	
Gate-Source Charge	Q_{gs}	-	2.5	-	nC		
Gate-Drain Charge	Q_{gd}	-	3.2	-	nC		
Turn-On Delay Time	t _{D(on)}	-	10.39	·	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$ $R_{GEN} = 6\Omega, I_D = 1A, R_1 = 10\Omega$	
Turn-On Rise Time	t _r	-	11.66	-	ns		
Turn-Off Delay Time	t _{D(off)}	-	59.38	-	ns		
Turn-Off Fall Time	t _f	-	16.27	·	ns		

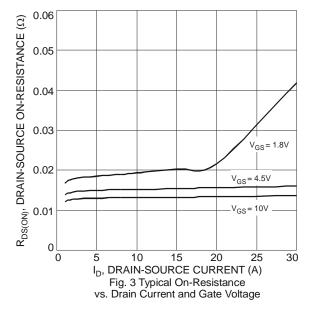
Notes: 5. Short duration pulse test used to minimize self-heating effect.

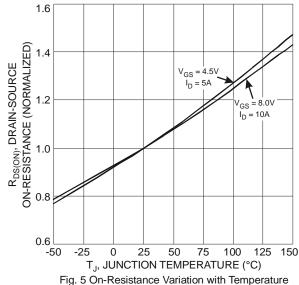
6. Guaranteed by design. Not subject to production testing.

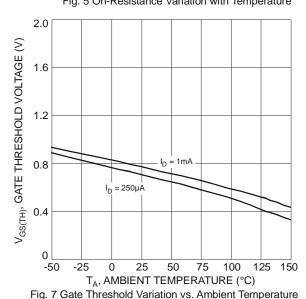












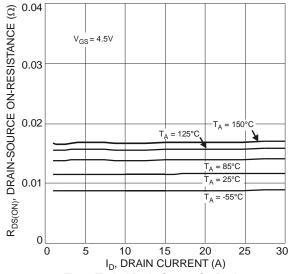


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

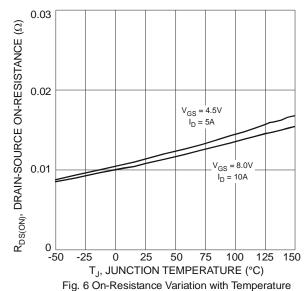
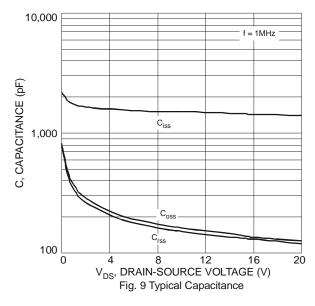
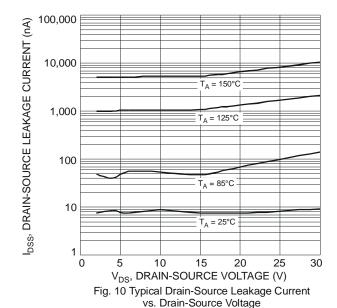
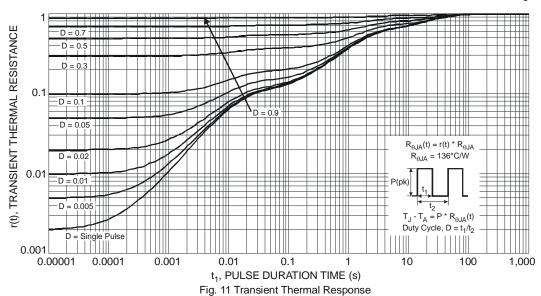


Fig. 8 Diode Forward Voltage vs. Current







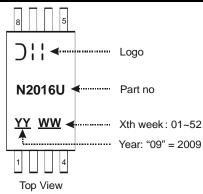


Ordering Information (Note 7)

Part Number	Case	Packaging
DMN2016UTS-13	TSSOP-8L	2500 / Tape & Reel

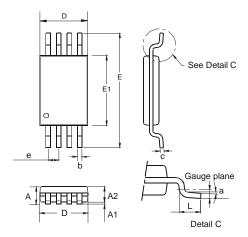
Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



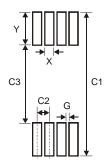


Package Outline Dimensions



TSSOP-8L					
Dim	Min	Max	Тур		
а	0.09	_	-		
Α	_	1.20	_		
A1	0.05	0.15	-		
A2	0.825	1.025	0.925		
b	0.19	0.30	_		
С	0.09	0.20	_		
D	2.90	3.10	3.025		
е	_	_	0.65		
Е	_	_	6.40		
E1	4.30	4.50	4.425		
L	0.45	0.75	0.60		
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Х	0.45
Y	1.78
C1	7.72
C2	0.65
C3	4.16
G	0.20



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